

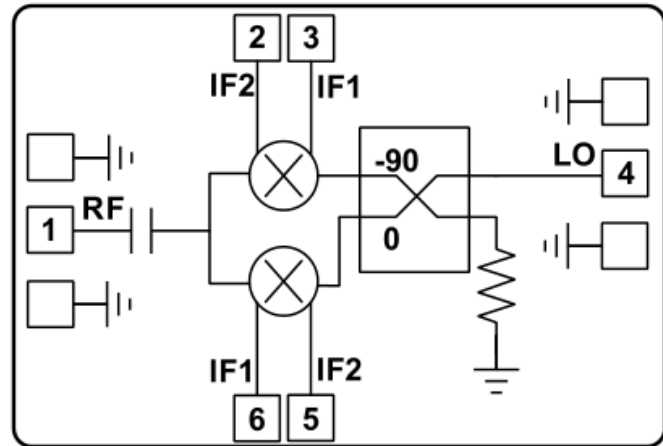
Features

- Passive Type: No DC biasing required
- RF Frequency: 15-23.6 GHz
- Conversion Loss: 9 dB
- Image Rejection 20 dB
- LO/RF Isolation: 45 dB
- IF Bandwidth: DC-3.5 GHz
- P1dB: +16 dBm
- Die Size: 1.49 x 1.14 x 0.1 mm

Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Functional Block Diagram



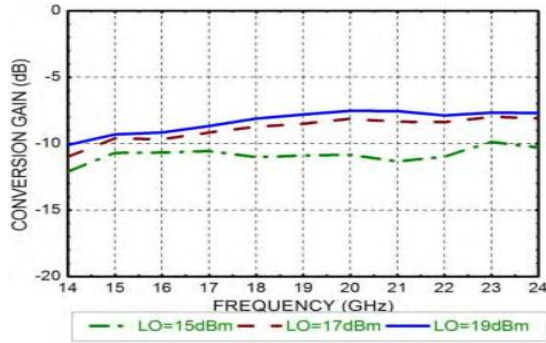
Electrical Specifications

TA = +25°C, If = 100MHz, Lo = +17dBm

Parameters	Min.	Typ.	Max.	Units
RF Frequency (RF/LO)		15-23.6		GHz
IF Frequency (IF)		DC-3.5		GHz
Conversion Loss		9		dB
Image Rejection		20		dB
Isolation "LO to RF"		45		dB
Isolation "LO to IF"		25		dB
Isolation "RF to IF"		50		dB
Input 1dB Compression		16		dBm
Input Third Order Intercept (IIP3)		24		dBm



Conversion Gain vs. LO Drive



Isolation

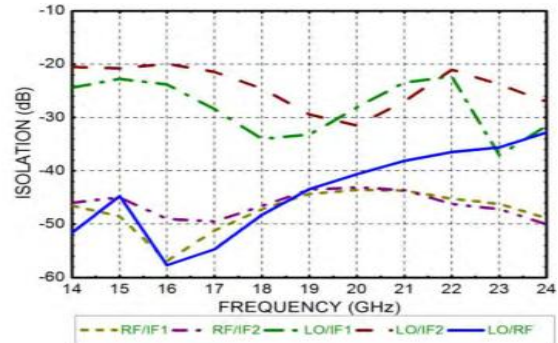
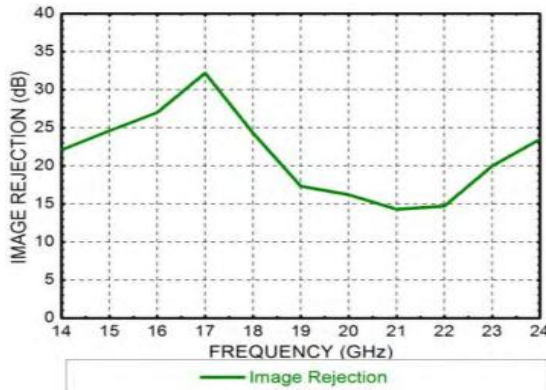
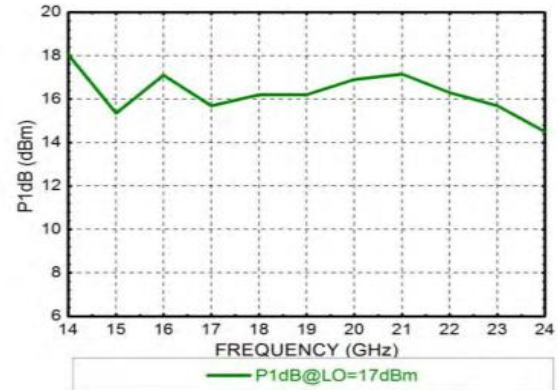


Image Rejection



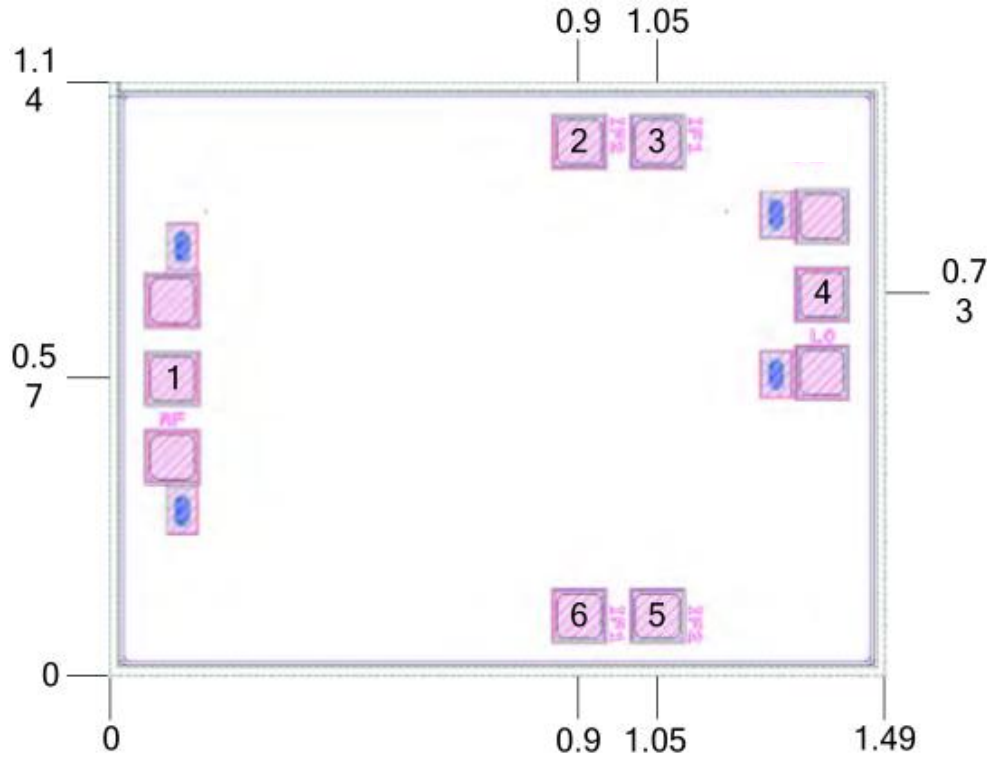
Input Power P1dB





Outline Drawing:

All Dimensions in mm



Pad Description

Pad Number	Function	Description
1	RF	AC coupling 50Ω Impedance
2,3,5,6	IF1, IF2	DC coupling 50Ω Impedance
4	LO	DC coupling 50Ω Impedance
Die bottom	GND	Die bottom must be connected to RF/DC ground.

Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die is grounded
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. RF/IF input power: +21dBm
2. Local oscillator drive power: +27dBm
3. Storage temperature: -65°C to +150°C
4. Operating temperature: -55°C to +85°C